

**IN THE CLAIMS:**

1. (Currently Amended). A module bridge system for smart labels for positioning chip modules (5) on carriers (12) and for the bridging connection of connection elements of the chip modules (5) to connection elements (11a, 11b) of antenna elements (11) arranged on or in the carriers (12), the module bridge system comprising:

a carrier strip; and

a plurality of module bridges (10) are arranged one behind the other on the carrier strip (1), wherein the carrier strip (1) has a plurality of depressions (2) arranged one behind the other for respectively receiving a chip module (5) assigned to a module bridge (10) and printed contact layers (7a, 7b), which cover the connection elements of the chip modules (5), with increased dimensions compared to the dimensions of the connection elements; and

adhesive layers (8a, 8b) applied to the printed contact layers (7a, 7b) for adhesively attaching individual module bridges (10) to the carriers (12) in the region of the connection elements (11a, 11b) of the antenna elements (11).

2. (Cancelled)

3. (Previously Presented). The module bridge system of Claim 1, wherein the printed contact layers (7a, 7b) are designed to be self-adhesive.

4. (Currently Amended). The module bridge system of Claim 1, wherein the printed contact layers (7a, 7b) ~~consist of~~ comprises a first ~~strip-like~~ contact layer which extends in a longitudinal direction of the carrier strip and covers first connection elements of first connection sides (5a) of the chip modules (5), and of a second ~~strip-like~~ contact layer which extends in the longitudinal direction of the carrier strip and covers second connection elements of second connection sides (5b) of the chip modules (5).

5. (Currently Amended). The module bridge system of Claim 4, wherein the first and second ~~strip-like~~ contact layers (7a, 7b) have interruptions (4) between the chip modules (5), said interruptions extending in the width direction of the carrier strip.

6. (Currently Amended). The module bridge system of Claim ~~[[2]]~~ 1, wherein the adhesive layers (8a, 8b) ~~consist of~~ comprises two ~~strip-like~~ adhesive layers (8a, 8b) with interruptions (4), said layers running parallel to one another in the longitudinal direction of the carrier strip.

7. (Previously Presented). The module bridge system of Claim 1, wherein the chip modules (5) are arranged within the depressions (2) by means of adhesive (9a, 9b).

8. (Previously Presented). The module bridge system of Claim 1, wherein the depressions (2) have a sufficient depth for arranging the chip modules (5) therein in such a way that their upper sides (5c) and a surface (1a) of the carrier strip (1) which surrounds the depressions (2) lie in one plane.

9. (Previously Presented). The module bridge system of Claim 1, wherein the depressions (2) are shaped to be complementary to outer shapes of the chip modules (5) to be received therein.

10. (Previously Presented). The module bridge system of Claim 1, wherein the depressions (2) in each case have at least one hole on the underside.

11. (Currently Amended). The module bridge system of Claim 1, wherein the ~~transport~~ carrier strip (1) has rows of holes (3) at the edge for the engagement of transport elements.

12. (Previously Presented). The module bridge system of Claim 1, wherein the carrier strip (1) is made of at least one of a deformable plastic and paper material.